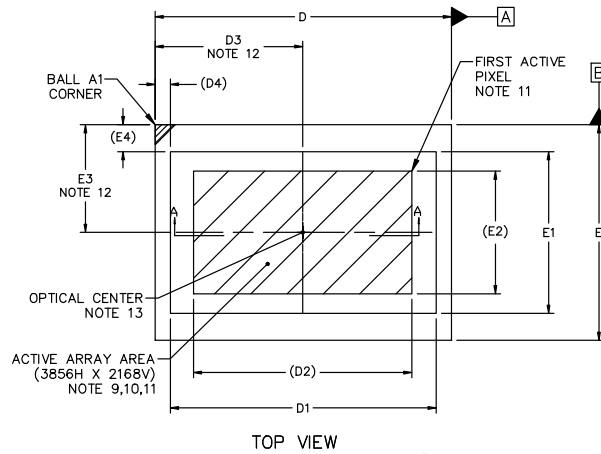
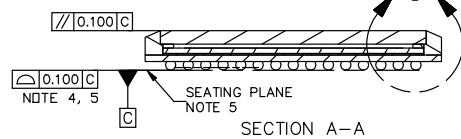


IBGA149 11.00x8.00x1.15, 0.65P
CASE 503CT
ISSUE B

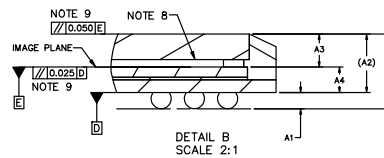
DATE 12 AUG 2025



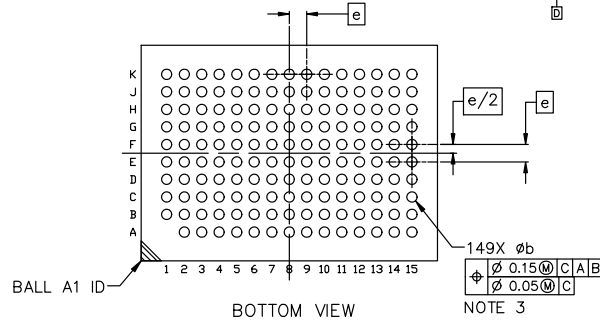
TOP VIEW



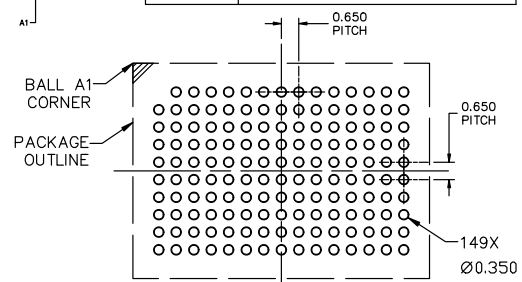
SECTION A-A



DETAIL B
SCALE 2:1



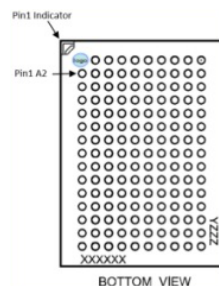
BOTTOM VIEW



RECOMMENDED MOUNTING FOOTPRINT*

* For additional information on our Pb-Free strategy and soldering details, please download the onsemi Soldering and Mounting Techniques reference manual, SOLDERRM/D.

GENERIC MARKING DIAGRAM*



BOTTOM VIEW

XXXX = Specific Device Code
Y = Year
ZZZ = Lot Traceability

NOTES:

- DIMENSIONING AND TOLERANCING PER ASME Y14.5M, 1994.
- CONTROLLING DIMENSION: MILLIMETERS [mm].
- SOLDER BALL DIAMETER IS MEASURED AT THE MAXIMUM SOLDER BALL DIAMETER PARALLEL TO DATUM C.
- COPLANARITY APPLIES TO THE SPHERICAL CROWNS OF THE SOLDER BALLS.
- DATUM C, THE SEATING PLANE IS DEFINED BY THE SPHERICAL CROWNS OF THE SOLDER BALLS.
- SOLDER BALL MATERIAL: SAC305 (96.5% Sn, 3% Ag, 0.5% Cu).
- GLASS: 0.500 THICKNESS; REFRACTIVE INDEX = 1.52; AR COATING R<1% 420-850nm (EACH SIDE).
- AIR GAP BETWEEN GLASS AND PIXEL ARRAY: 0.150 THICKNESS.
- PARALLELISM APPLIES ONLY TO THE ACTIVE ARRAY.
- MAXIMUM ROTATION OF ACTIVE ARRAY RELATIVE TO DATUMS A AND B IS $\pm 0.7^\circ$.
- REFER TO THE DEVICE DATA SHEET FOR TOTAL PIXEL ARRAY DEFINITIONS.
- PACKAGE CENTER (X, Y) = (0.000, 0.000).
- OPTICAL CENTER RELATIVE TO PACKAGE CENTER (X, Y) = (-0.023, 0.000).

*This information is generic. Please refer to device data sheet for actual part marking. Pb-Free indicator, "G" or microdot "▪", may or may not be present. Some products may not follow the Generic Marking.

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